

Listing of Claims:

1. (Previously presented): Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating that prevents solder adherence.
2. (Previously presented): Electronic component as in Claim 1 or 28 or 29 or 30 or 31, characterized in that the anti-solder coating essentially consists of siloxane.
3. (Previously presented): Electronic component as in Claim 1, characterized in that the anti-solder coating essentially consists of polysiloxane.
4. (Previously presented): Electronic component as in Claim 1 or 28 or 29 or 30 or 31, characterized in that the anti-solder coating is essentially based on methyl-polysiloxane.
5. (Previously presented): Electronic component as in Claim 1 or 28 or 29 or 30 or 31, characterized in that the anti-solder coating is essentially based on dimethyl-polysiloxane.
6. (Previously presented): Electronic component as in Claim 1 or 28 or 29 or 30 or 31, characterized in that the anti-solder coating is essentially based on polyether-modified dimethyl-polysiloxane.

7. (Previously presented): Electronic component as in claim 1, characterized in that the plastic housing contains a radiation-emitting and/or radiation-detecting semi-conductor element that is embedded in transparent plastic for the emitted and/or received radiation.

Claims 8-26 (Cancelled)

27. (Previously presented): Electronic component as in claim 1 wherein said component is a surface-mountable radiation-emitting and/or radiation-sensitive electro-optical component.

28. (Previously presented): Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating, wherein said component is an unsoldered component, said anti-solder coating preventing solder adherence.

29. (Previously presented): Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating prior to soldering of said component at said soldering area, said anti-solder coating preventing solder adherence.

30. (Previously presented): Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating, wherein said component is apart from any support structure, said anti-solder coating preventing solder adherence.

31. (Previously presented): Electronic component having a plastic housing that includes at least one metallic soldering area, characterized in that the surface of the plastic housing, except for the metallic soldering area, is at least partially covered by an anti-solder coating, wherein said coating has an end, and said coating ends at said component, said anti-solder coating preventing solder adherence.